

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Hui et al.

Docket No.: TI-27874

Serial No: TBD

Examiner: TBD

Filed: 10/18/01

Art Unit: TBD

For: DIE PAD FOR INTEGRATED CIRCUITS

~~S. Stevens~~
43/9
12-10-01

PRELIMINARY AMENDMENT

October 18, 2001

Assistant Commissioner for Patents

Washington, DC 20231

Dear Sir:

Please amend the above referenced application as follows:

In the Specification:

Page 1, before line 1, insert --This application claims priority under 35 USC §

91 119(e)(1) of provisional application numbers 60/254,567 filed 12/11/00.--